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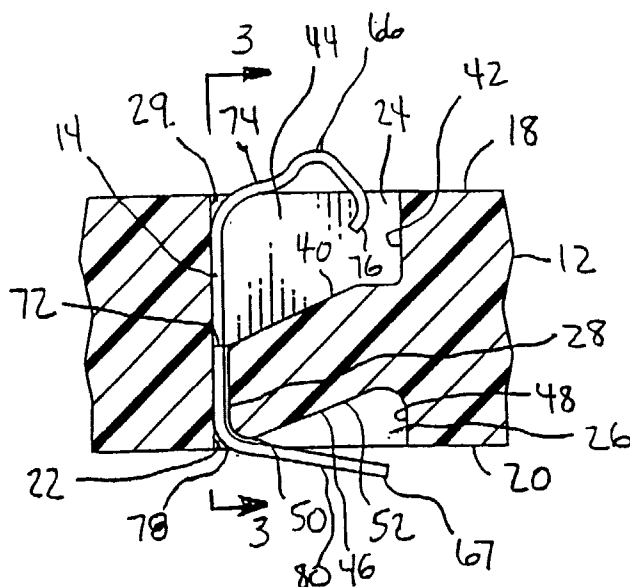
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(54) Title: INTERPOSER ASSEMBLY FOR SOLDERED ELECTRICAL CONNECTIONS



(57) Abstract: An interposer assembly (10) includes an insulating plate (12) with passages (16) extending through the thickness of the plate and metal contacts (14) in the passages. The contacts have resilient upper and lower contact arms (62, 64) that deflect into upper and lower recesses (24, 26) of the plate when sandwiched between contact pads of overlying and underlying circuit members. The recesses are sized to accommodate solder connections between contact arms and contact pads.



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